

FIG._3A

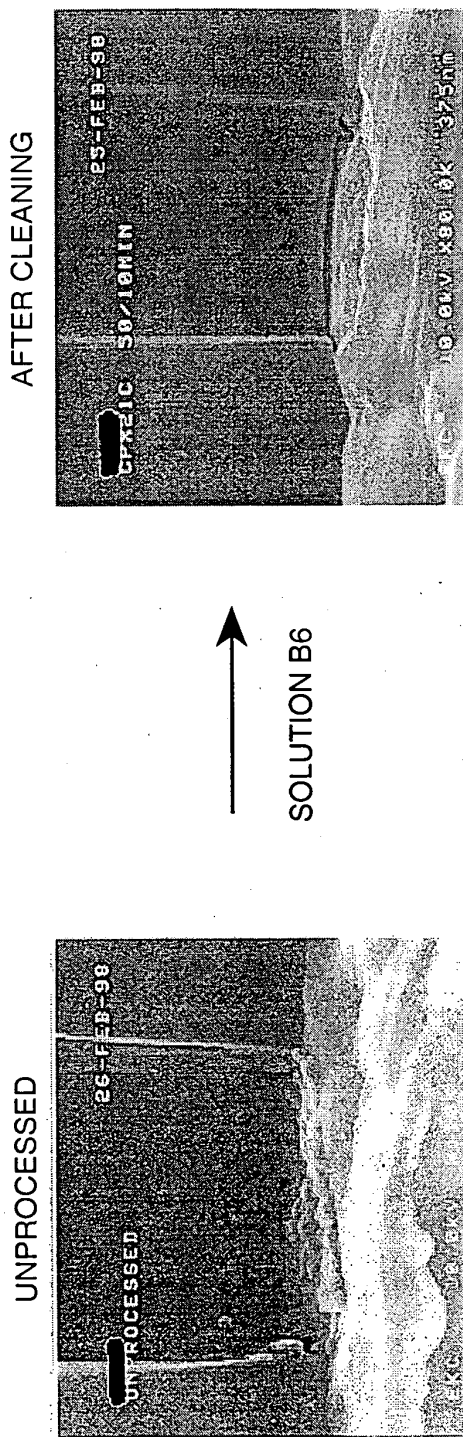


FIG._3B

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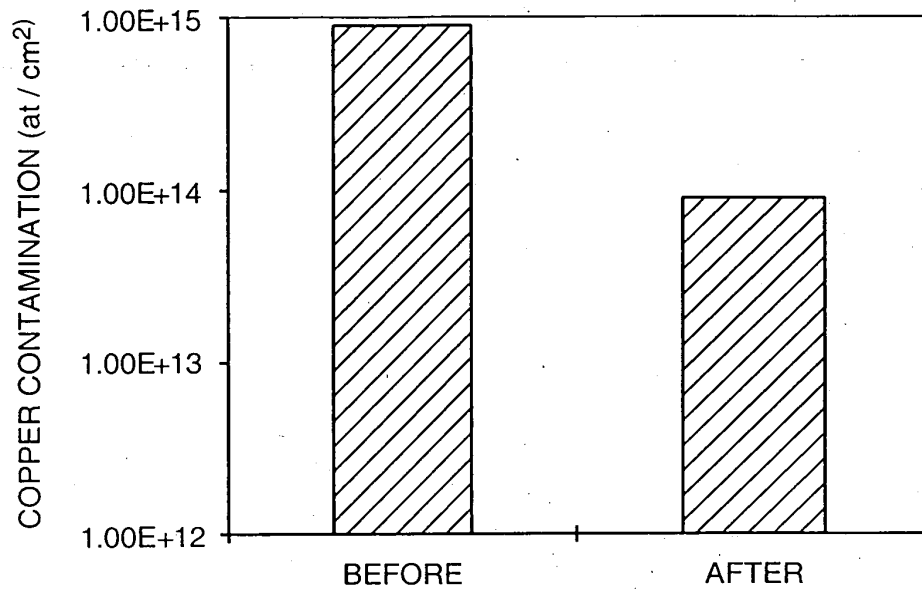


FIG._4

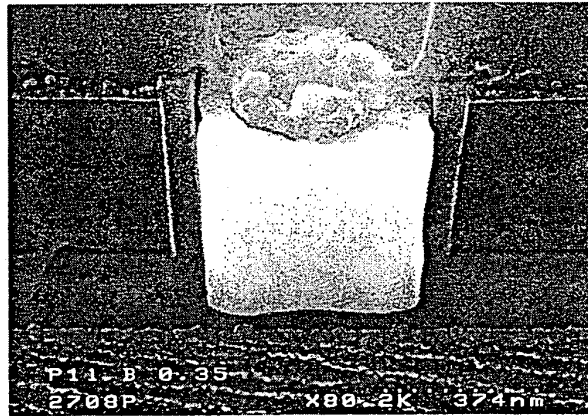


FIG._5

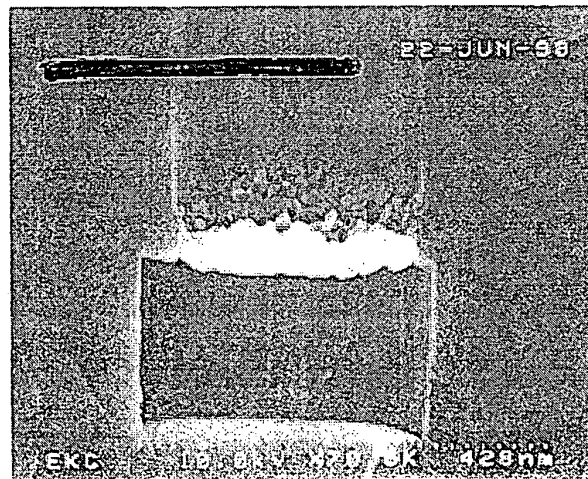
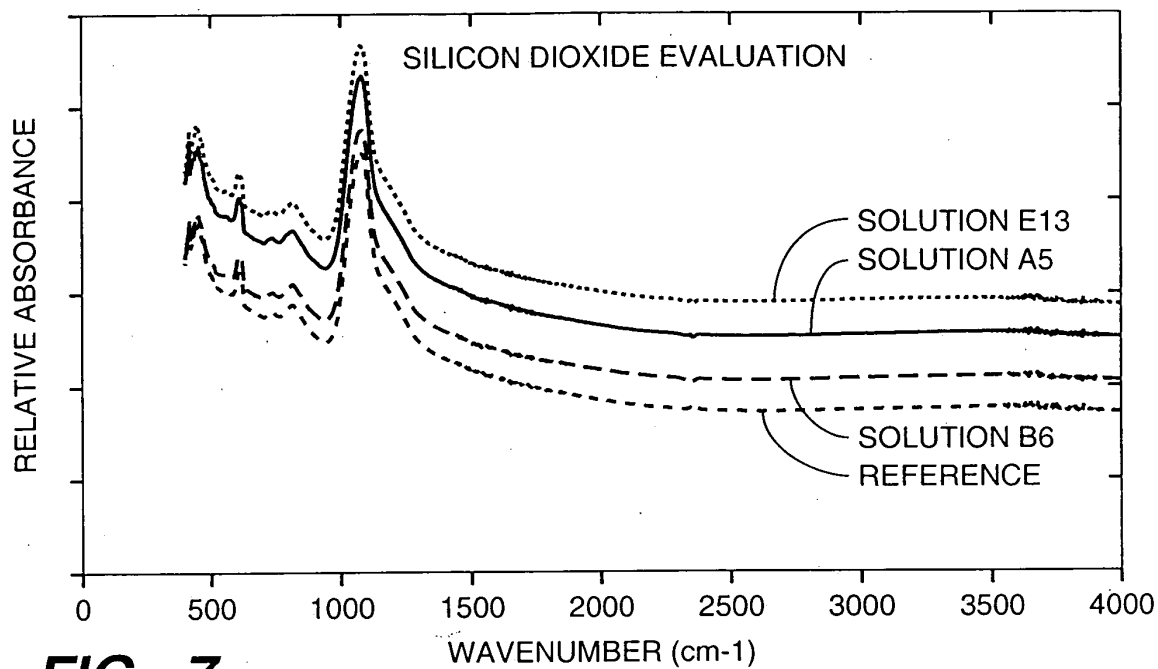
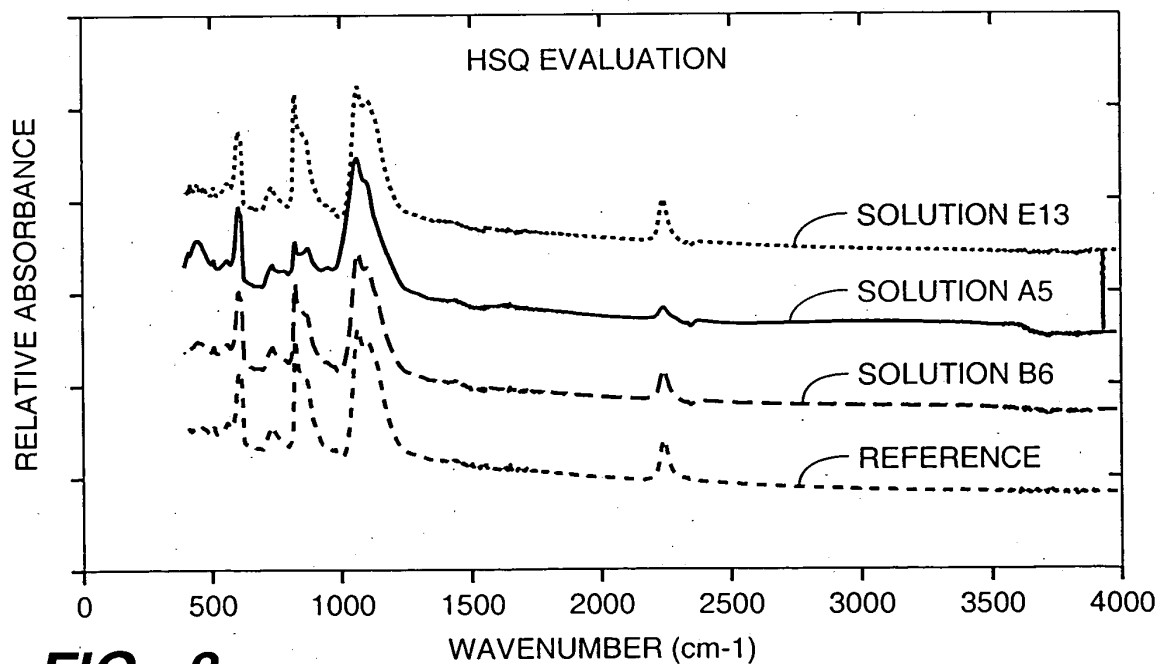


FIG._6

**FIG._7****FIG._8**

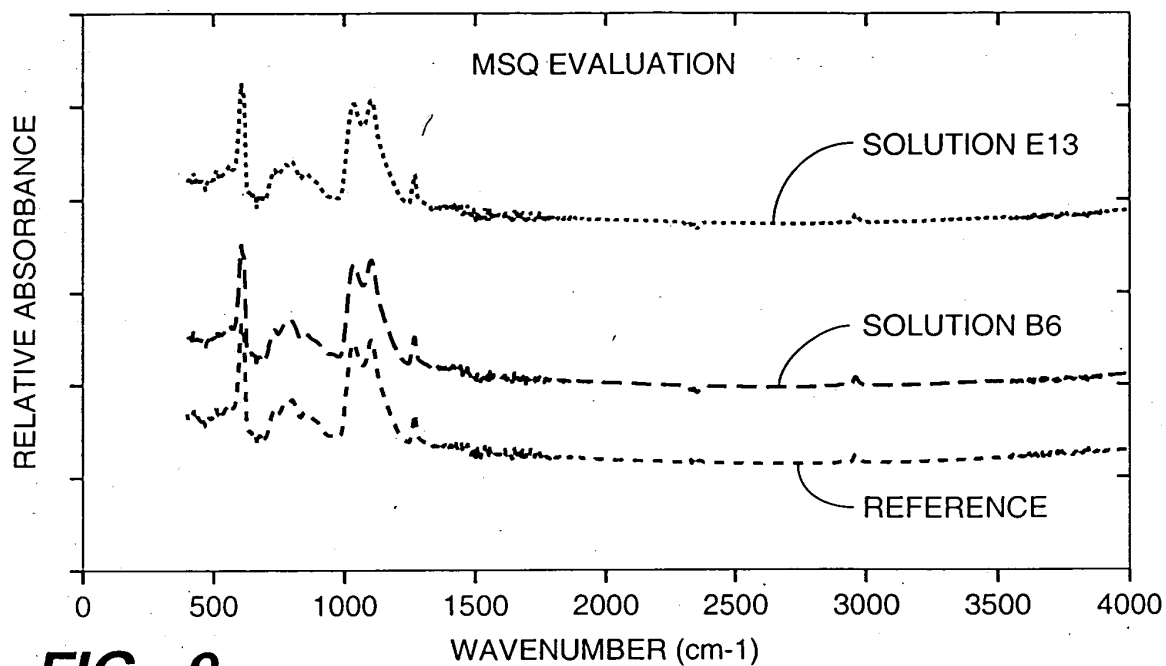


FIG._9

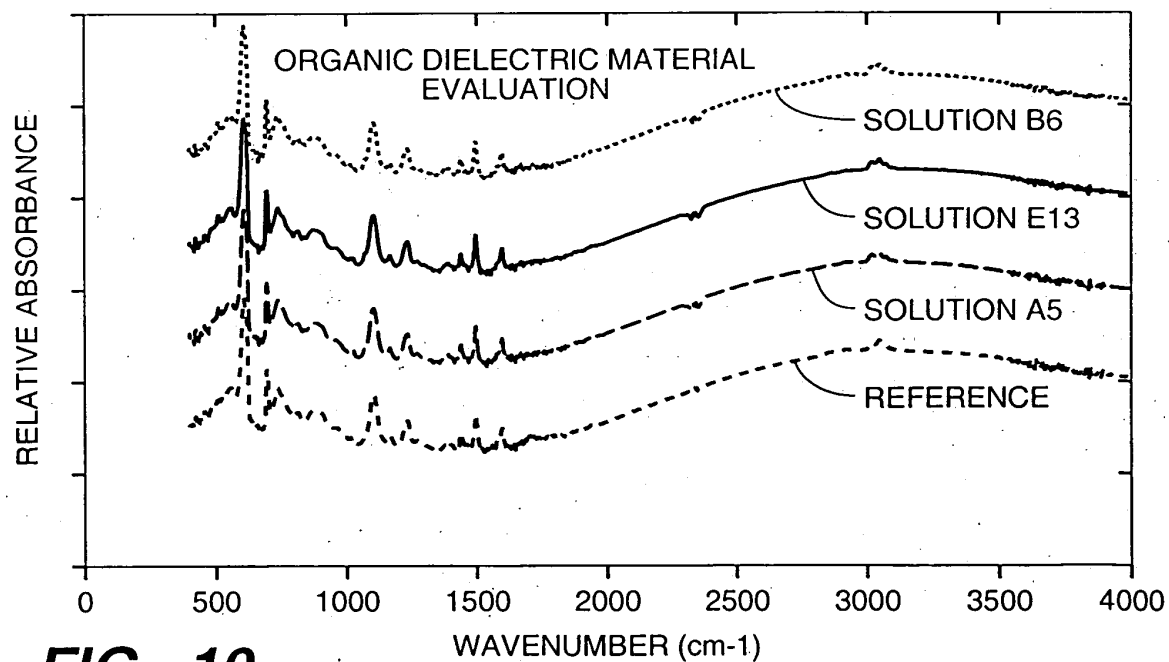


FIG._10

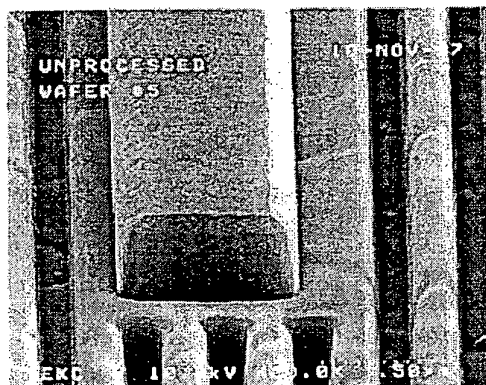


FIG._11

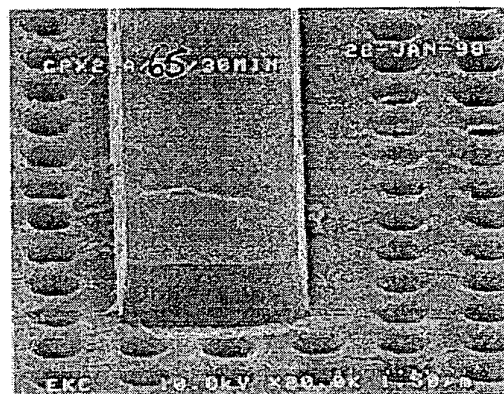


FIG._12

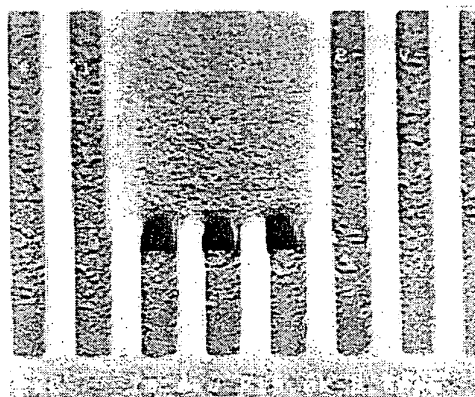


FIG._13

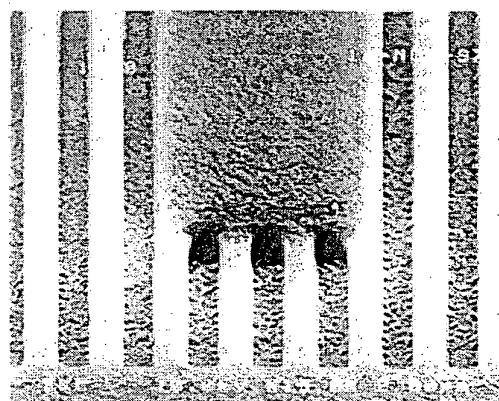


FIG._14

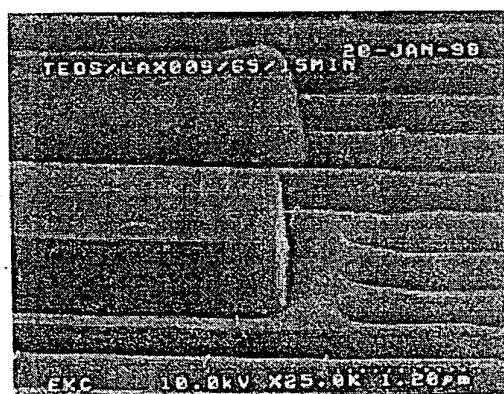


FIG._15

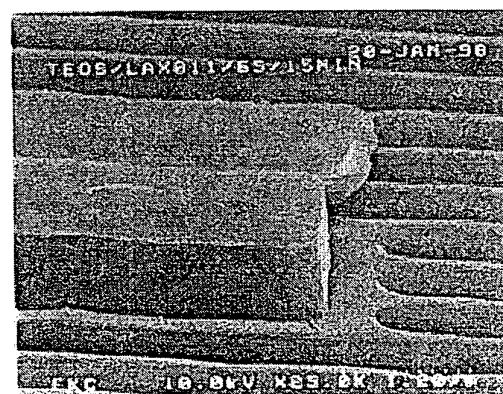


FIG._16



FIG._17

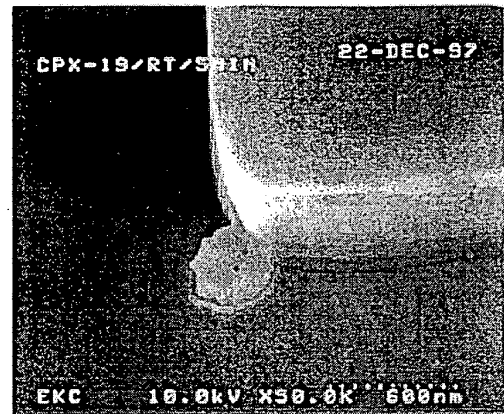


FIG._18

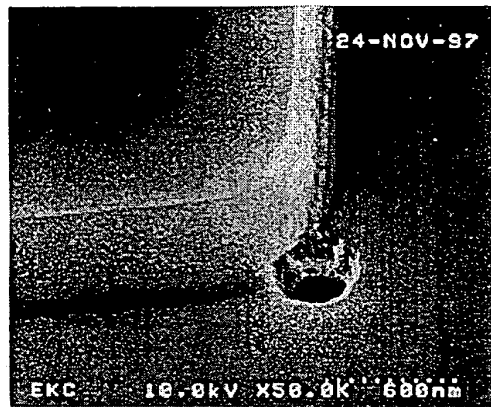


FIG._19



FIG._20

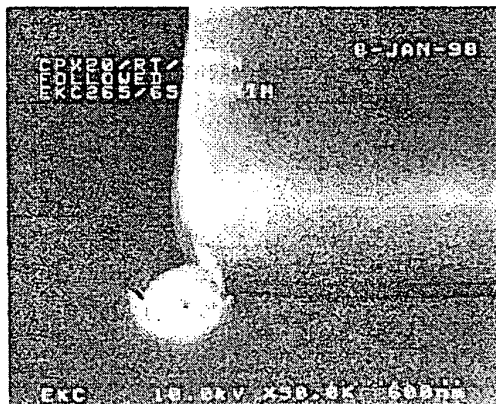


FIG._21

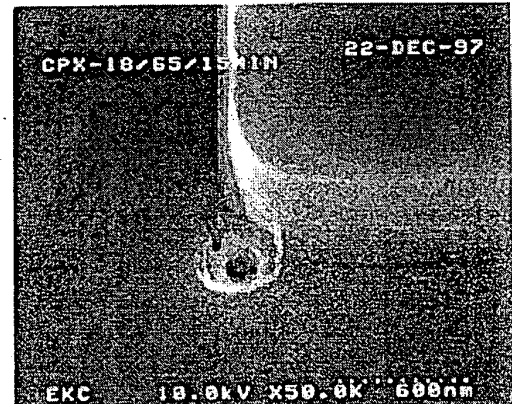
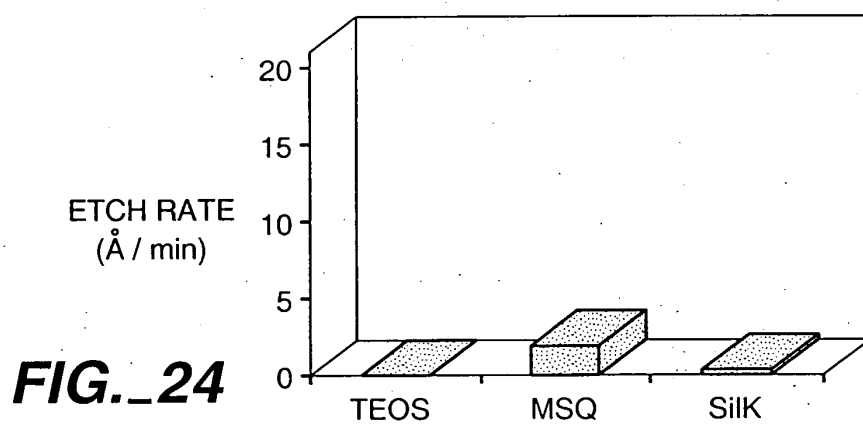
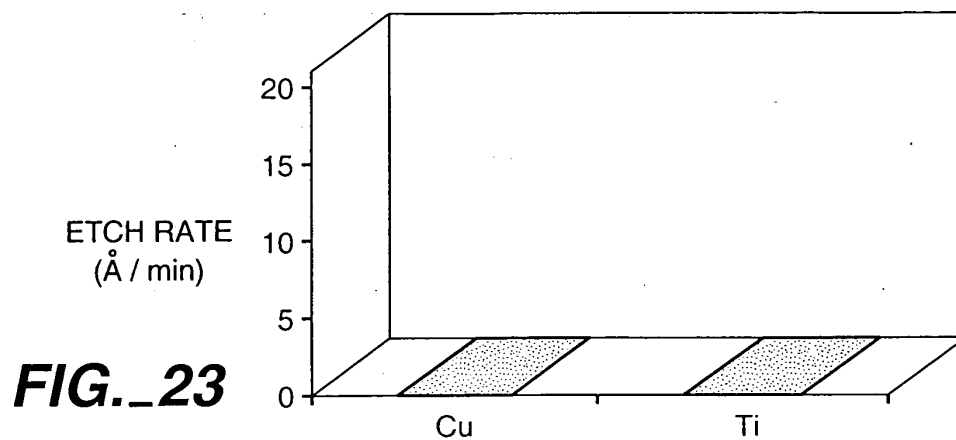


FIG._22



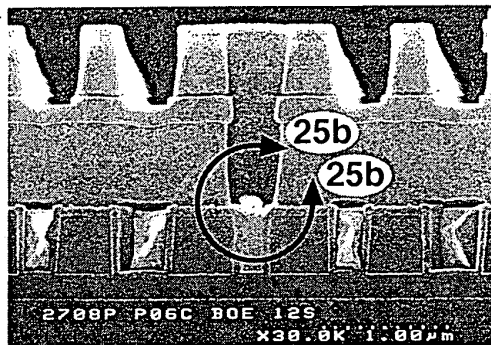


FIG._25a



FIG._25b

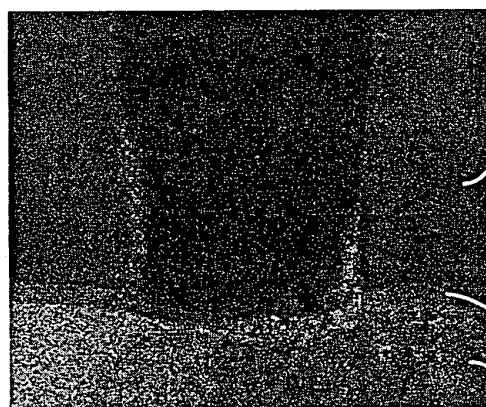


FIG._26

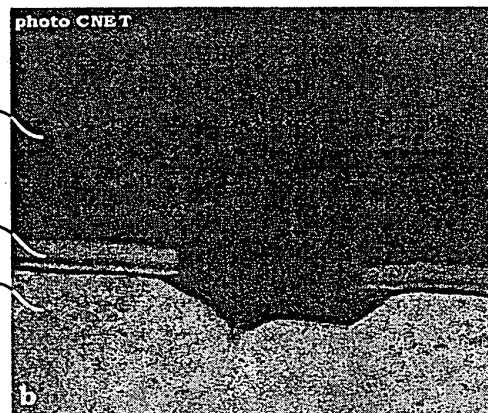


FIG._27

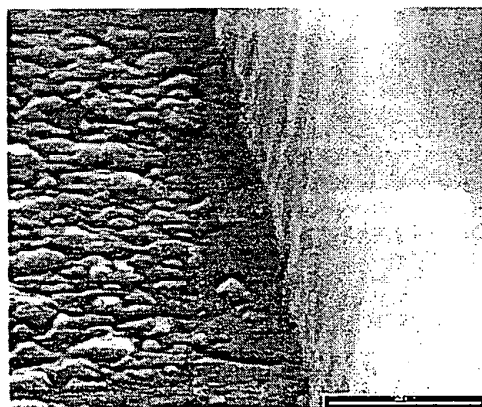


FIG._28

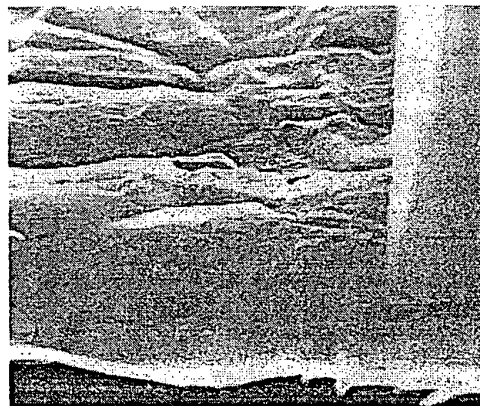


FIG._29

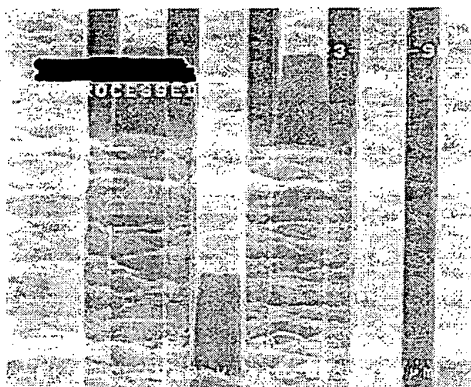


FIG._30

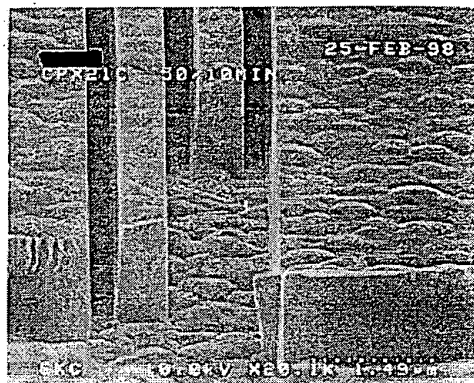


FIG._31

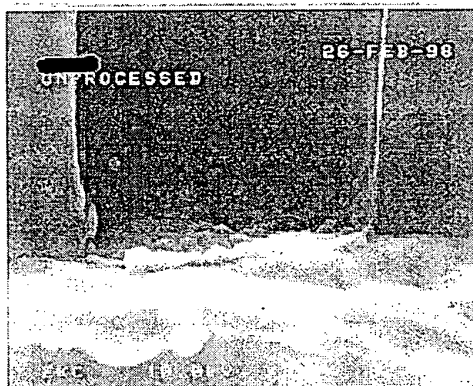


FIG._32

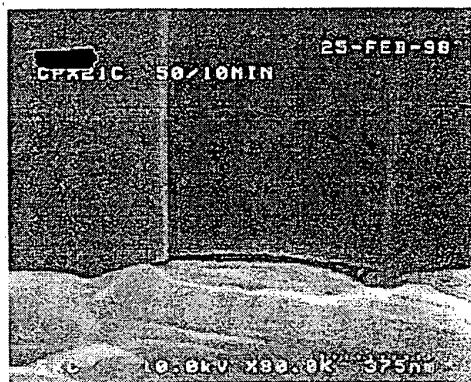


FIG._33



FIG._36

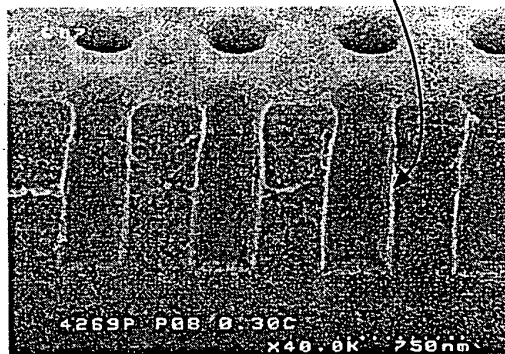


FIG._37

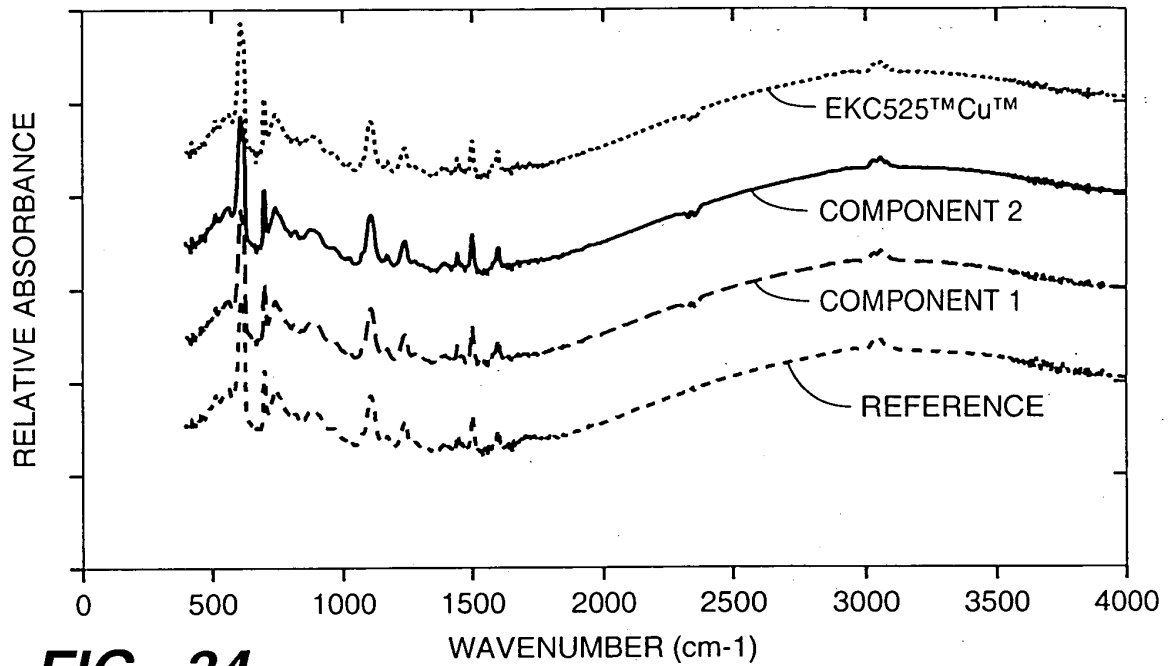


FIG._34

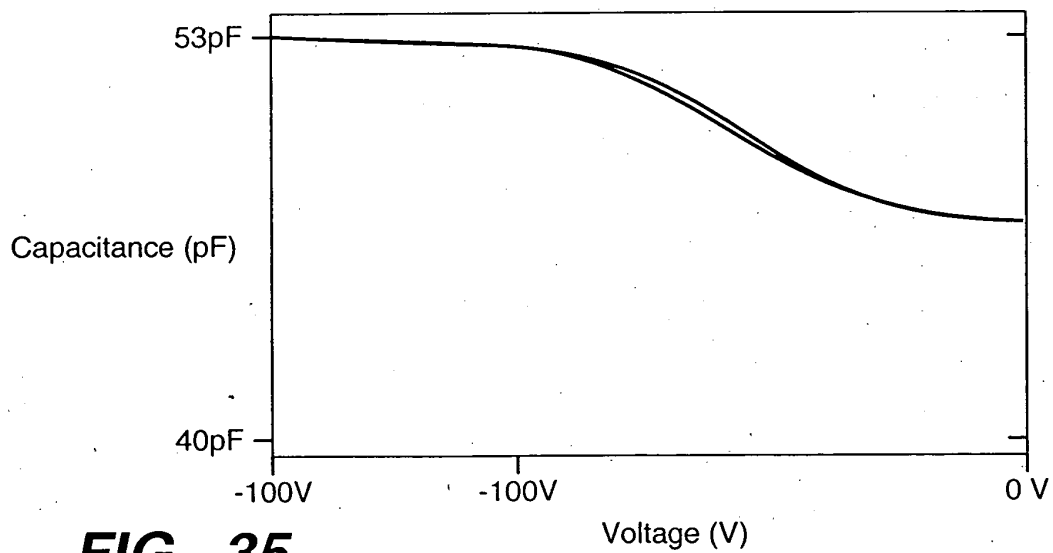
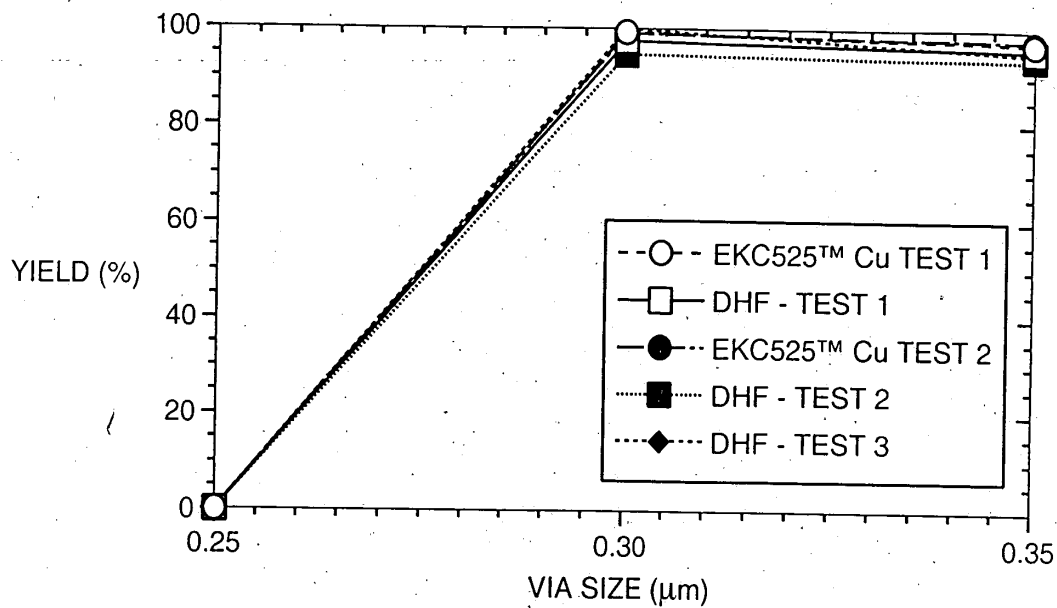
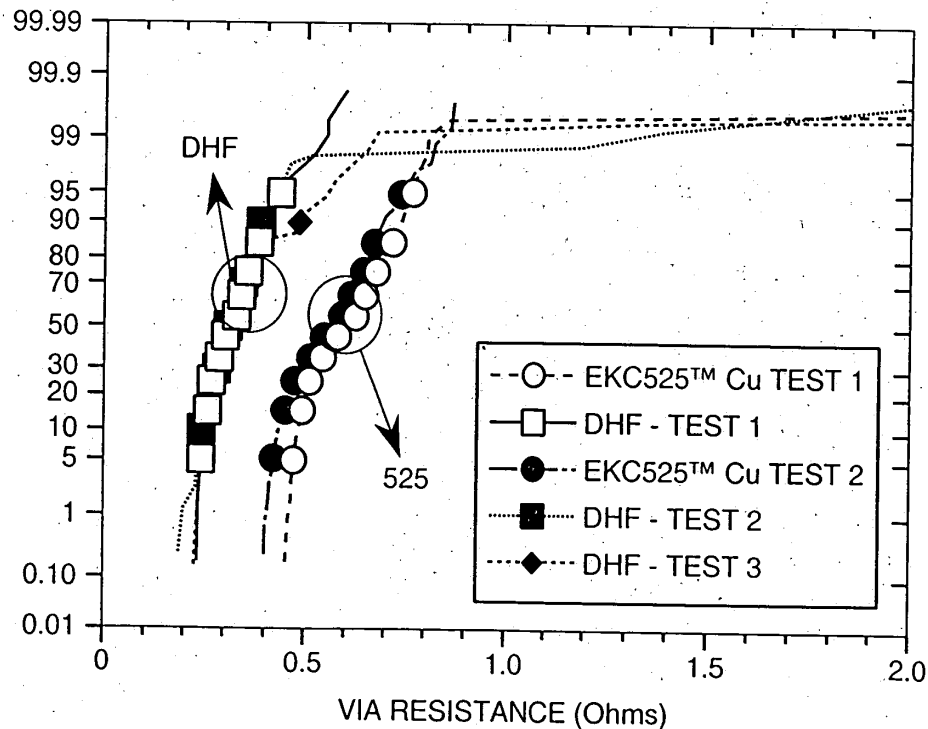
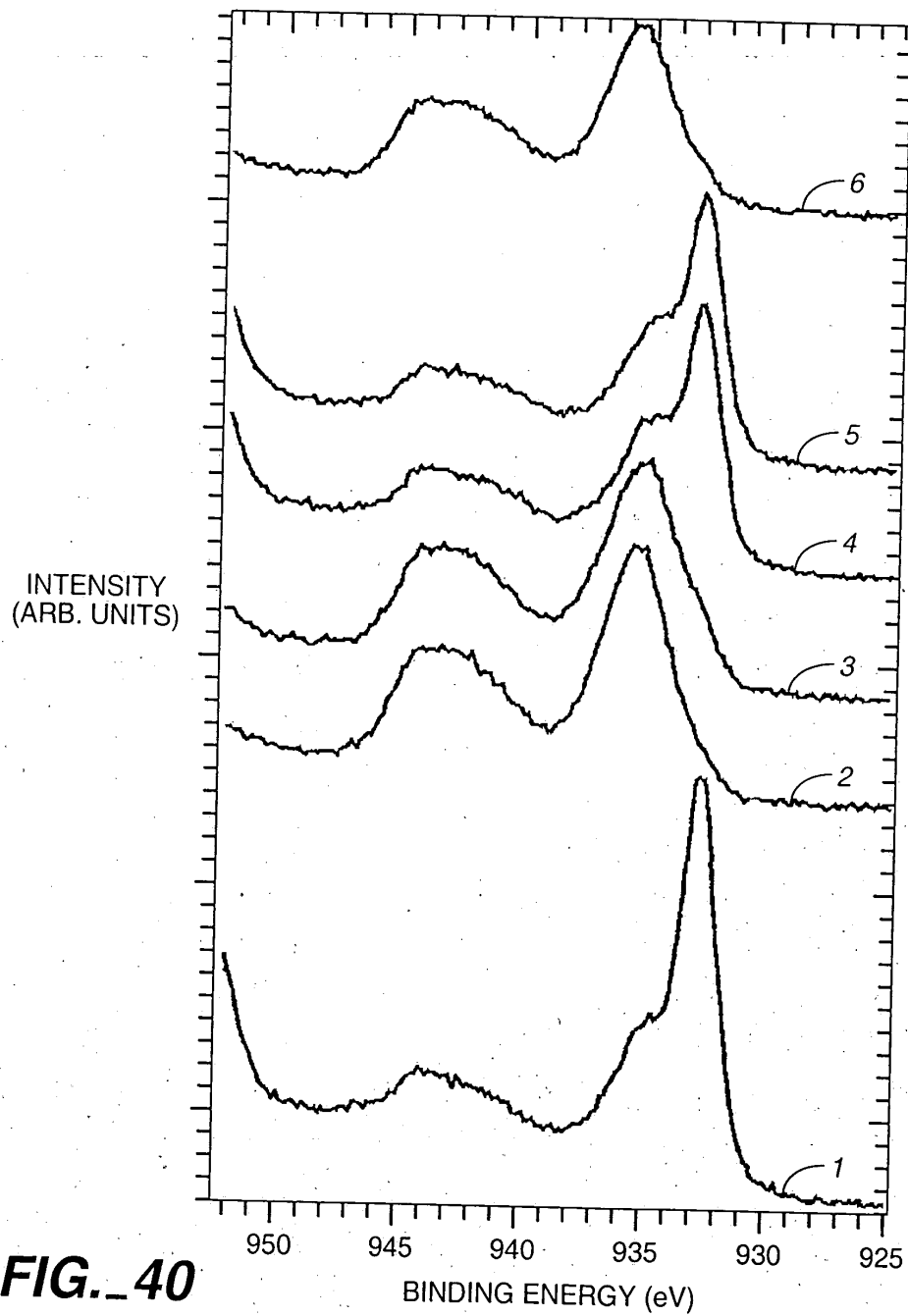


FIG._35

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**FIG. 38**YIELD RESULTS ON COPPER TEOS
STRUCTURE VERSUS VIA SIZE
COMPARING DHF AND CLEANING SOLUTION**FIG. 39**VIA RESISTANCE HISTOGRAM FOR 0.3 μm VIAS
COMPARING DHF AND CLEANING SOLUTION

**FIG. 40**

XPS ANALYSIS OF THE SURFACE COMPOSITION
OF A COPPER BLANKET BEFORE (1), AFTER
ETCHING (2 AND 3) AND AFTER CLEANING IN
THE SOLUTION (4 AND 5) AND IN SOLUTION B8 (6).